## **600V N-Channel MOSFET**

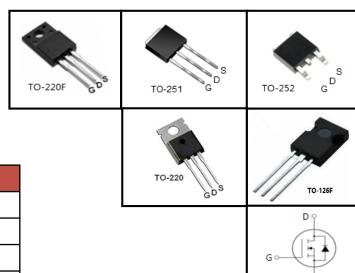
#### **FEATURES**

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Device Marking and Package Information							
Device	Package	Marking					
CS2N60F	TO-220F	CS2N60F					
CS2N60P	TO-220	CS2N60P					
CS2N60U	TO-251	CS2N60U					
CS2N60D	TO-252	CS2N60D					
CS2N60C	TO-126F	CS2N60C					



<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted								
		Value						
Parameter	Symbol	TO- 220F	TO- 126F	TO- 220	TO- 251	TO- 252	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>			600			V	
Continuous Drain Current	I <sub>D</sub>	2				А		
Pulsed Drain Current (note1)	I <sub>DM</sub>	8					Α	
Gate-Source Voltage	$V_{GSS}$			±20			V	
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	28.8				mJ		
Avalanche Current (note1)	I <sub>AS</sub>	2.4				Α		
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	17.28				mJ		
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	20	)		25		W	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150				°C		

Thermal Resistance							
Parameter		Value					
	Symbol	TO- 220F	TO- 126F	TO- 251	TO- 252	TO- 220	Unit
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	6.25		5			K/W
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62.5		60			



			Value			
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_{D} = 250\mu A$	600			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 600V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μΑ
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 20V$			±100	nA
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		4.0	V
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_{D} = 1.0A$		3.5	4.2	Ω
Dynamic						
Input Capacitance	C <sub>iss</sub>	V 0V		249.5		pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = 25V,$		30		
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		4.2		
Total Gate Charge	$Q_g$			11		nC
Gate-Source Charge	$Q_gs$	$V_{DD} = 480V, I_{D} = 2.0A,$ $V_{GS} = 10V$		1.55		
Gate-Drain Charge	$Q_gd$	- GS 101		6.15		
Turn-on Delay Time	t <sub>d(on)</sub>			33.6		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 250V, I_{D} = 2.0A,$		7.2		ns
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 25 \Omega$		64		
Turn-off Fall Time	t <sub>f</sub>			31.2		
Drain-Source Body Diode Character	istics					
Continuous Body Diode Current	Is	T 0500			2	
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			8	A
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}\text{C}, I_{SD} = 2.0\text{A}, V_{GS} = 0\text{V}$			1.4	V
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 2.0A,$		490		ns
Reverse Recovery Charge	Q <sub>rr</sub>	di <sub>F</sub> /dt =100A /μs		0.6		μC

#### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 10.0mH,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25  $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%

## **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted

Figure 1. Output Characteristics (T<sub>J</sub> = 25°C)

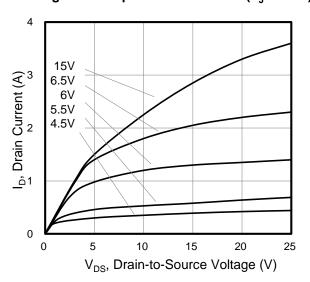


Figure 3. Drain Current vs. Temperature

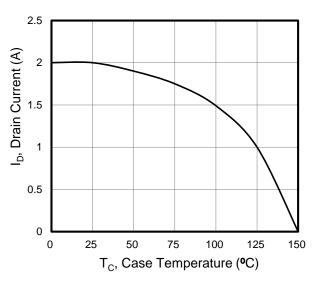


Figure 5. Transfer Characteristics

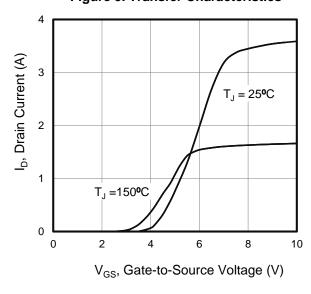
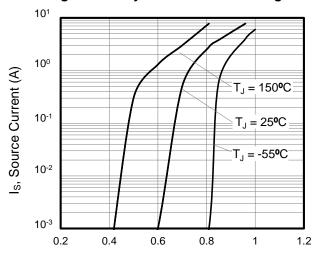


Figure 2. Body Diode Forward Voltage



V<sub>SD</sub>, Source-to-Drain Voltage (V)

Figure 4. Power Dissipation vs. Temperature TO-251,TO-252

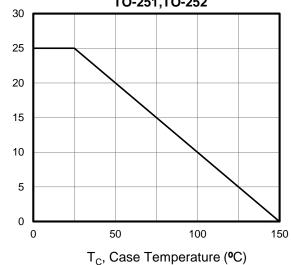
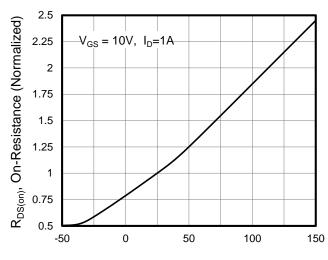


Figure 6. On-Resistance vs. Temperature



T<sub>J</sub>, Junction Temperature (°C)

P<sub>D</sub>, Power Dissipation (w)



#### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

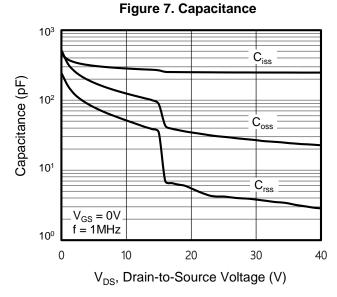


Figure 8. Gate Charge

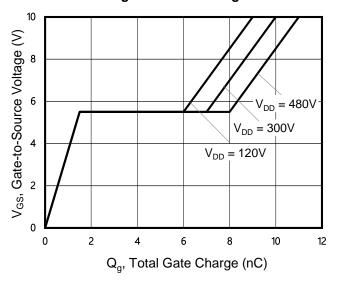


Figure 9. Transient Thermal Impedance

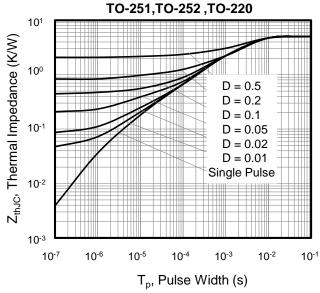


Figure 10. Transient Thermal Impedance TO-220F, TO-126F

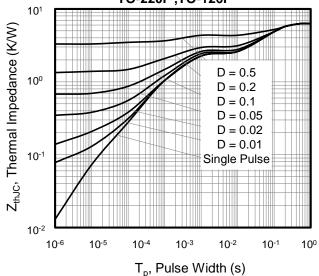




Figure A: Gate Charge Test Circuit and Waveform

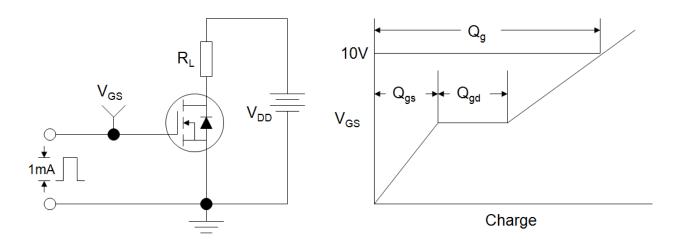


Figure B: Resistive Switching Test Circuit and Waveform

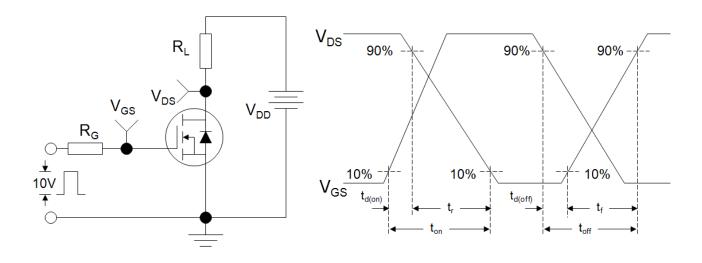
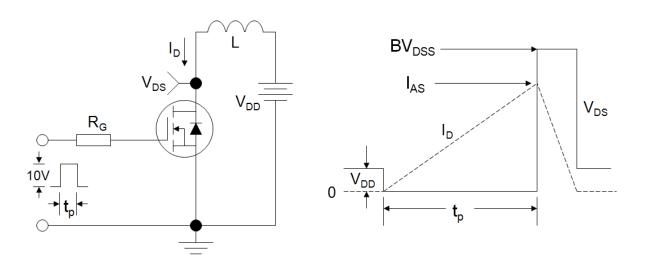
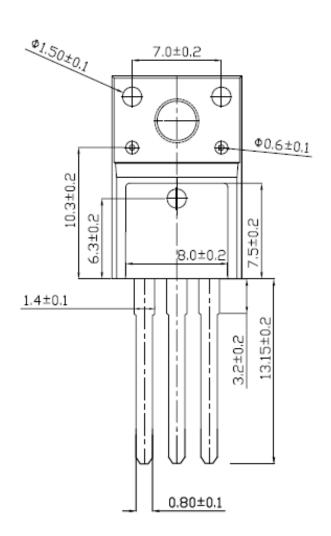
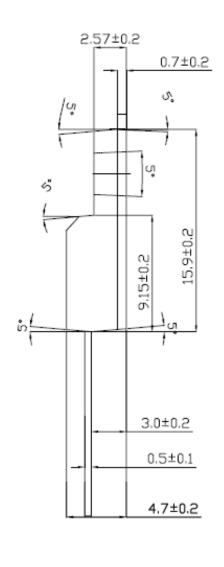


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



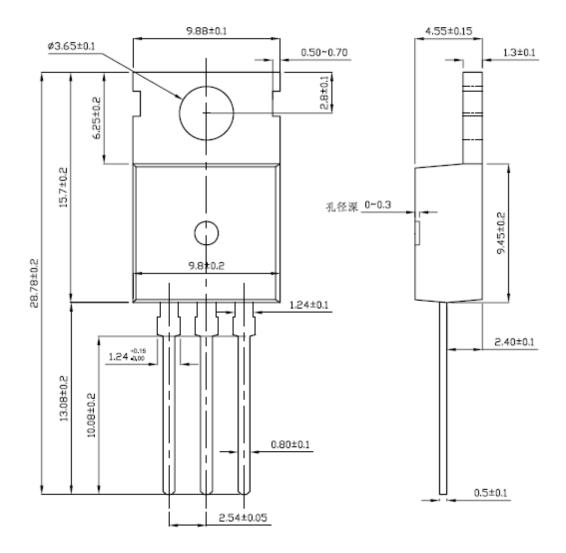
## **TO-220F**



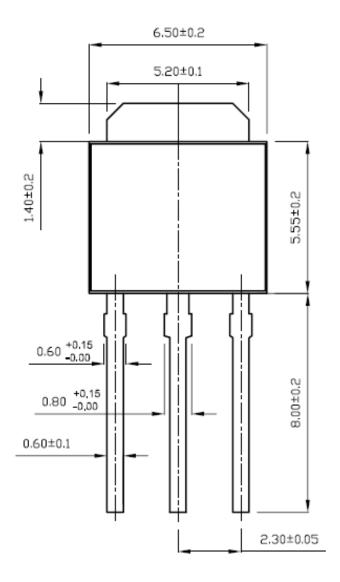


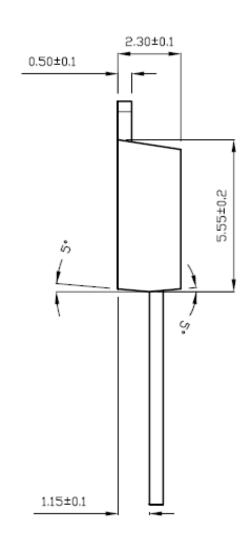


## **TO-220**

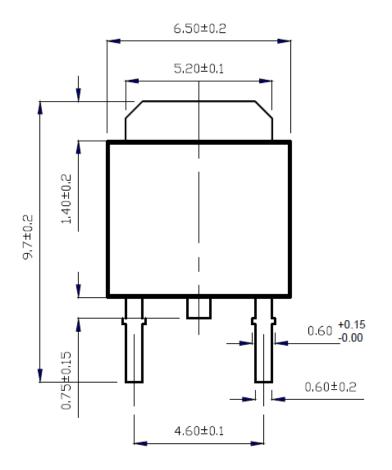


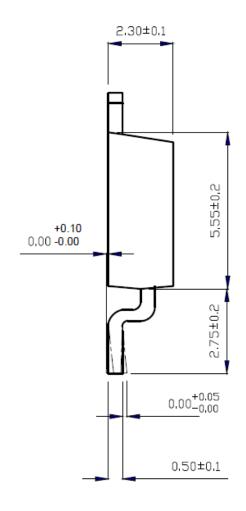
**TO-251** 





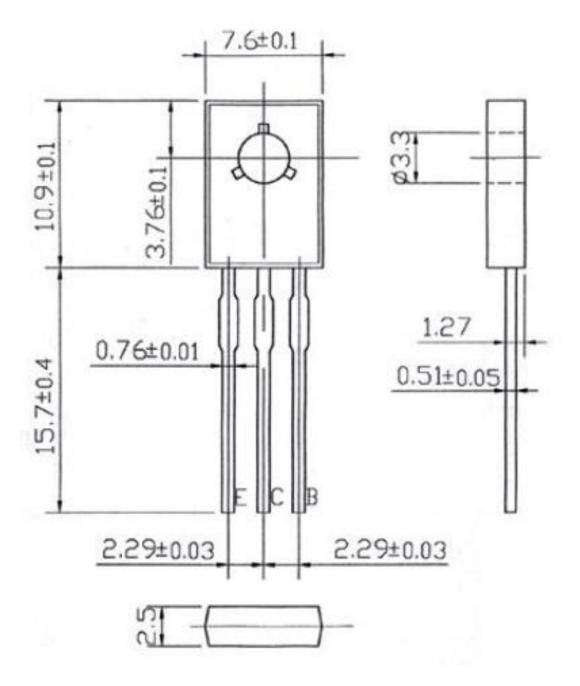
## **TO-252**







## **TO-126F**





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